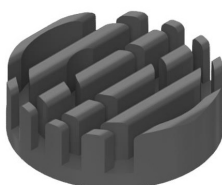


Data sheet Product ICK LED R 33 x 10 G



Heatsinks and active heatsinks for processors>Heatsinks for LEDs
 Ø 33 x 10 mm, for IC design LED

Features

diameter:	33 mm
way of fixation:	• therm. conductive foil • therm. cond. adhesive
height:	10 mm
plate thickness:	3 mm
thermal resistance:	18.15 - 3.8 K/W
dissipation loss:	6.6 W
surface:	black anodised

Technical Drawing

